

Title (en)

Cross-hatched polishing pad for polishing substrates in a chemical mechanical polishing system

Title (de)

Schraffiertes Polierkissen zum Polieren eines Halbleitersubstrats in einem chemisch- mechanischen Poliersystem

Title (fr)

Patin de polissage haché pour polir un substrat dans un système de polissage chemico-mécanique

Publication

EP 0806267 A1 19971112 (EN)

Application

EP 97302999 A 19970501

Priority

US 64305496 A 19960502

Abstract (en)

A chemical mechanical polishing apparatus (30) including a platen (42) having a polishing surface (44) having a plurality of grooves (330,302) defining a plurality of polygonal projections (330). The grooves are uniformly spaced over the entire area of the polishing surface. A carrier head holds the substrate against the polishing surface. <IMAGE>

IPC 1-7

B24B 37/04

IPC 8 full level

B24B 37/00 (2006.01); **B24B 37/04** (2006.01); **B24B 37/26** (2012.01); **B24D 13/14** (2006.01); **H01L 21/304** (2006.01)

CPC (source: EP KR)

B24B 37/26 (2013.01 - EP); **H01L 21/306** (2013.01 - KR)

Citation (search report)

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